



## Film Capacitors

### Metallized Polypropylene Film Capacitors (MKP)

**Series/Type:** B32794 ... B32798

**Date:** February 2010

**MKP AC filtering**
**Preliminary Data**
**Typical applications**

- Output AC filtering for power converters  
UPS, solar inverters, motor drives

**Climatic**

- Max. operating temperature: 105 °C
- Climatic category (IEC 60068-1): 40/85/56

**Construction**

- Dielectric: Polypropylene (PP)
- Plastic case (UL 94 V-0)
- Epoxy resin sealing (UL 94 V-0)

**Features**

- Optimized AC voltage performance
- High ripple current/frequency capability
- Small dimensions
- For PCB mounting

**Terminals**

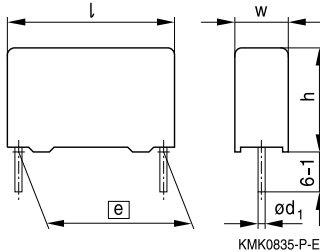
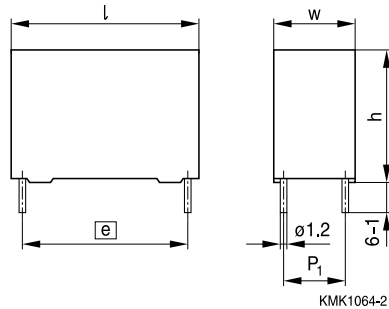
- Parallel wire leads, lead-free tinned
- 2-pin and 4-pin versions
- Standard lead lengths: 6 – 1 mm
- Special lead lengths available on request

**Marking**

Manufacturer's logo, date code,  
rated capacitance (coded), capacitance  
tolerance (code letter), rated AC voltage

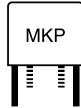
**Delivery mode**

Bulk (untaped, lead length 6 – 1 mm)

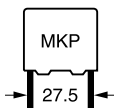
**Dimensional drawings**
**2-pin version**

**4-pin version**


Dimensions in mm

Version	Lead spacing $[e] \pm 0.4$	Lead diameter $d_1$	Type
2-pin	27.5	0.8	B32794D
2-pin	37.5	1.0	B32796E
4-pin	37.5	1.2	B32796G
4-pin	52.5	1.2	B32798G


**Preliminary Data**
**Overview of available types**

Lead spacing	27.5 mm				37.5 mm				52.5 mm			
Type	B32794				B32796				B32798			
Page	4				5				6			
$V_{RMS}$ (V AC)	250	300	350	400	250	300	350	400	250	300	350	400
$C_R$ ( $\mu$ F)												
0.82												
1.2												
1.5												
2.0												
2.2												
2.5												
3.3												
3.5												
4.0												
5.0												
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45												
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75												


**B32794**
**MKP AC filtering**
**Preliminary Data**
**Ordering codes and packing units (lead spacing 27.5 mm)**

$V_{RMS}$	$V_R$	$C_R$	Max. dimensions $w \times h \times l$	$P_1$	Ordering code (composition see below)	$I_{RMS}$ 60 °C 10 kHz A	ESL	ESR 10 kHz	Untaped
V AC	V DC	$\mu F$	mm	mm			nH	m $\Omega$	pcs./ MOQ
250	630	2.5	11.0 × 19.0 × 31.5	–	B32794D2255+000	4	24	14.1	2352
		4.0	11.0 × 21.0 × 31.5	–	B32794D2405+000	6	25	9.1	2352
		6.3	15.0 × 24.5 × 31.5	–	B32794D2635+000	8	26	6.1	1680
		10	16.0 × 32.0 × 31.5	–	B32794D2106+000	11	27	4.2	1064
		15	22.0 × 36.5 × 31.5	–	B32794D2156+000	13	28	3.1	784
300	700	2.0	11.0 × 19.0 × 31.5	–	B32794D3205+000	4	24	15.6	2352
		3.3	13.5 × 23.0 × 31.5	–	B32794D3335+000	6	25	9.7	1932
		5.0	14.0 × 24.5 × 31.5	–	B32794D3505+000	7	26	6.7	1848
		8.0	18.0 × 33.0 × 31.5	–	B32794D3805+000	9	27	4.6	952
		12	22.0 × 36.5 × 31.5	–	B32794D3126+000	11	28	3.5	784
350	875	1.2	11.0 × 19.0 × 31.5	–	B32794D8125+000	3	24	21.2	2352
		2.2	12.5 × 21.5 × 31.5	–	B32794D8225+000	5	25	11.9	2100
		3.3	15.0 × 24.5 × 31.5	–	B32794D8335+000	7	26	8.2	1680
		5.0	18.0 × 33.0 × 31.5	–	B32794D8505+000	9	27	5.8	952
		7.5	22.0 × 36.5 × 31.5	–	B32794D8755+000	12	28	4.5	784
400	1050	0.82	11.0 × 19.0 × 31.5	–	B32794D4824+000	3	24	26.5	2352
		1.5	13.5 × 23.0 × 31.5	–	B32794D4155+000	4	25	14.8	1932
		2.2	14.0 × 24.5 × 31.5	–	B32794D4225+000	6	26	10.4	1848
		3.5	18.0 × 33.0 × 31.5	–	B32794D4355+000	8	27	6.9	952
		5.0	22.0 × 36.5 × 31.5	–	B32794D4505+000	11	28	5.5	784

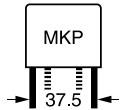
MOQ = Minimum Order Quantity, consisting of 4 packing units.  
Further E series and intermediate capacitance values on request.

**Composition of ordering code**

+ = Capacitance tolerance code:

K =  $\pm 10\%$

J =  $\pm 5\%$


**Preliminary Data**
**Ordering codes and packing units (lead spacing 37.5 mm)**

$V_{RMS}$	$V_R$	$C_R$	Max. dimensions w × h × l	$P_1$	Ordering code (composition see below)	$I_{RMS}$ 60 °C 10 kHz A	ESL nH	ESR 10 kHz mΩ	Untaped pcs./ MOQ
V AC	V DC	μF	mm	mm					
250	630	22	20.0 × 39.5 × 42.0	10.2	B32796G2226+000	15	30	3.2	640
		22	20.0 × 39.5 × 42.0	—	B32796E2226+000	14	30	3.2	640
		25	28.0 × 37.0 × 42.0	10.2	B32796G2256+000	17	30	2.9	440
		25	28.0 × 37.0 × 42.0	—	B32796E2256+000	16	30	2.9	440
		40	30.0 × 45.0 × 42.0	20.3	B32796G2406+000	21	33	2.3	400
		40	30.0 × 45.0 × 42.0	—	B32796E2406+000	20	33	2.3	400
		45	33.0 × 48.0 × 42.5	20.3	B32796G2456+000	23	33	1.9	192
300	700	16	20.0 × 39.5 × 42.0	10.2	B32796G3166+000	14	30	3.9	640
		16	20.0 × 39.5 × 42.0	—	B32796E3166+000	13	30	3.9	640
		20	28.0 × 37.0 × 42.0	10.2	B32796G3206+000	15	30	3.1	440
		20	28.0 × 37.0 × 42.0	—	B32796E3206+000	14	30	3.1	440
		30	30.0 × 45.0 × 42.0	20.3	B32796G3306+000	19	33	2.2	400
		30	30.0 × 45.0 × 42.0	—	B32796E3306+000	18	33	2.2	400
		34	33.0 × 48.0 × 42.5	20.3	B32796E3346+000	20	33	1.9	192
350	875	10	20.0 × 39.5 × 42.0	10.2	B32796G8106+000	12	30	4.9	640
		10	20.0 × 39.5 × 42.0	—	B32796E8106+000	11	30	4.9	640
		14	28.0 × 37.0 × 42.0	10.2	B32796G8146+000	15	30	3.6	440
		14	28.0 × 37.0 × 42.0	—	B32796E8146+000	14	30	3.6	440
		15	30.0 × 45.0 × 42.0	20.3	B32796G8156+000	15	30	3.0	400
		20	30.0 × 45.0 × 42.0	20.3	B32796G8206+000	19	30	2.6	400
		20	30.0 × 45.0 × 42.0	—	B32796E8206+000	18	30	2.6	400
24	33.0 × 48.0 × 42.5	20.3	B32796G8246+000	20	30	2.5	192		
400	1050	7.5	20.0 × 39.5 × 42.0	10.2	B32796G4755+000	11	30	5.5	640
		7.5	20.0 × 39.5 × 42.0	—	B32796E4755+000	10	30	5.5	640
		10	28.0 × 37.0 × 42.0	10.2	B32796G4106+000	14	30	4.5	440
		10	28.0 × 37.0 × 42.0	—	B32796E4106+000	13	30	4.5	440
		13	30.0 × 45.0 × 42.0	20.3	B32796G4136+000	17	33	3.5	400
		13	30.0 × 45.0 × 42.0	—	B32796E4136+000	16	33	3.5	400
		16	33.0 × 48.0 × 42.5	20.3	B32796G4166+000	18	33	3.5	192

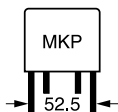
MOQ = Minimum Order Quantity, consisting of 4 packing units.  
Further E series and intermediate capacitance values on request.

**Composition of ordering code**

+ = Capacitance tolerance code:

K = ±10%

J = ±5%


**B32798**
**MKP AC filtering**
**Preliminary Data**
**Ordering codes and packing units (lead spacing 52.5 mm)**

$V_{RMS}$	$V_R$	$C_R$	Max. dimensions w × h × l	$P_1$	Ordering code (composition see below)	$I_{RMS}$ 60 °C 10 kHz A	ESL nH	ESR 10 kHz mΩ	Untaped pcs./ MOQ
V AC	V DC	μF	mm	mm					
250	630	55	30.0 × 45.0 × 57.5	20.3	B32798G2556+000	21	35	2.7	280
		75	35.0 × 50.0 × 57.5	20.3	B32798G2756+000	25	38	2.1	108
300	700	40	30.0 × 45.0 × 57.5	20.3	B32798G3406+000	19	35	3.2	280
		55	35.0 × 50.0 × 57.5	20.3	B32798G3556+000	24	38	2.5	108
350	875	26	30.0 × 45.0 × 57.5	20.3	B32798G8266+000	18	35	4.5	280
		30	35.0 × 50.0 × 57.5	20.3	B32798G8306+000	20	37	4.0	108
		35	35.0 × 50.0 × 57.5	20.3	B32798G8356+000	22	38	3.0	108
		40	35.0 × 50.0 × 57.5	20.3	B32798G8406K000	22	38	3.0	108
400	1050	18	30.0 × 45.0 × 57.5	20.3	B32798G4186+000	16	35	4.7	280
		20	35.0 × 50.0 × 57.5	20.3	B32798G4206+000	17	37	4.5	108
		25	35.0 × 50.0 × 57.5	20.3	B32798G4256+000	20	38	3.5	108

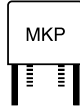
MOQ = Minimum Order Quantity, consisting of 4 packing units.  
Further E series and intermediate capacitance values on request.

**Composition of ordering code**

+ = Capacitance tolerance code:

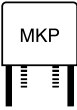
K = ±10%

J = ±5%


**Preliminary Data**
**Technical data**

Reference standard: IEC 61071

Operating temperature range (case)	Max. operating temperature, $T_{op,max}$ +105 °C Upper category temperature $T_{max}$ +85 °C Lower category temperature $T_{min}$ -40 °C Note: At $T > 85$ °C de-rating for $V_{RMS}$ (V AC) should be 1.5%/°C
Capacitance drift in range (-40 °C, -85 °C)	2% respect the value measured at reference conditions
Insulation Resistance $R_{ins}$ given as time constant $\tau = C_R \cdot R_{ins}$ , rel. humidity $\leq 65\%$ (minimum as-delivered values)	30 000 s
Test voltage between terminals	$1.5 \cdot V_R$ for 10 s $1.65 \cdot V_R$ for 2 s
DC test voltage terminal to case (10 s)	$2 \cdot V_{RMS} + 1000$ V AC (min. 2000 V AC) at 50 Hz
Maximum permissible overvoltage for short operating periods (max 1 min/day)	$1.3 \cdot V_{RMS}$
Maximum peak current (A)	$I_{P,max} = C_R \cdot \frac{dV}{dt}$
Damp heat test Limit values after damp heat test	56 days/40 °C/93% relative humidity Capacitance change $ \Delta C/C  \leq 5\%$ Dissipation factor change $\Delta \tan \delta \leq 1.5 \cdot 10^{-3}$ (at 1 kHz) Insulation resistance $R_{ins} \geq 50\%$ of minimum as-delivered values
Change of temperature	In accordance with IEC 60068-2-14 (Test Nb)
Reliability:	Failure rate $\lambda$ 300 fit Service life $t_{SL}$ > 60 000 h at $V_{RMS}$ For conversion to other operating conditions, refer to chapter "Reliability" on page 439 from Data Book 2009. Failure criteria: Total failure Short/open circuit Failure due to variation of parameters Capacitance change $ \Delta C/C  \geq 10\%$ Dissipation factor change $\Delta \tan \delta > 4 \cdot$ upper limit value Insulation resistance $R_{ins} < 1500$ M $\Omega$ ( $C_R \leq 0.33\mu F$ ) or time constant $\tau = C_R \cdot R_{ins} < 500$ s ( $C_R > 0.33\mu F$ )


**B32794 ... B32798**
**MKP AC filtering**
**Preliminary Data**
**Pulse handling capability**

"dV/dt" represents the maximum permissible voltage change per unit of time for non-sinusoidal voltages, expressed in V/μs.

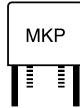
*Note:*

*The values of dV/dt provided below must not be exceeded in order to avoid damaging the capacitor.*

Lead spacing	27.5 mm				37.5 mm				52.5 mm			
Type	B32794				B32796				B32798			
V <sub>RMS</sub> (V AC)	250	300	350	400	250	300	350	400	250	300	350	400
	dV/dt in V/μs											
	27	31	39	47	19	21	26	32	12	14	18	21

**Notes:** Please take all additional data not mentioned above from our Data Book 2009




**Preliminary Data**
**Mounting guidelines**
**1 Soldering**
**1.1 Solderability of leads**

The solderability of terminal leads is tested to IEC 60068-2-20, test Ta, method 1.

Before a solderability test is carried out, terminals are subjected to accelerated ageing (to IEC 60068-2-2, test Ba: 4 h exposure to dry heat at 155 °C). Since the ageing temperature is far higher than the upper category temperature of the capacitors, the terminal wires should be cut off from the capacitor before the ageing procedure to prevent the solderability being impaired by the products of any capacitor decomposition that might occur.

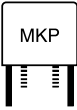
Solder bath temperature	235 ±5 °C
Soldering time	2.0 ±0.5 s
Immersion depth	2.0 +0/-0.5 mm from capacitor body or seating plane
Evaluation criteria:	
Visual inspection	Wetting of wire surface by new solder ≥90%, free-flowing solder

**1.2 Resistance to soldering heat**

Resistance to soldering heat is tested to IEC 60068-2-20, test Tb, method 1A.

Conditions:

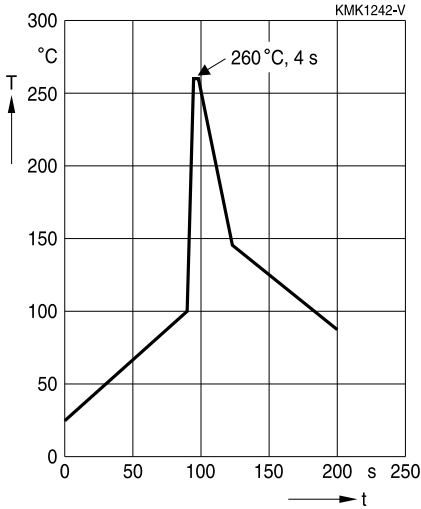
Series	Solder bath temperature	Soldering time
MKT boxed (except 2.5 × 6.5 × 7.2 mm) coated uncoated (lead spacing > 10 mm)	260 ±5 °C	10 ±1 s
MFP MKP (lead spacing > 7.5 mm)		
MKT boxed (case 2.5 × 6.5 × 7.2 mm)		5 ±1 s
MKP (lead spacing ≤ 7.5 mm)		< 4 s
MKT uncoated (lead spacing ≤ 10 mm) insulated (B32559)		recommended soldering profile for MKT uncoated (lead spacing ≤ 10 mm) and insulated (B32559)



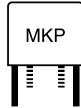
**B32794 ... B32798**

**MKP AC filtering**

**Preliminary Data**



Immersion depth	2.0 +0/−0.5 mm from capacitor body or seating plane
Shield	Heat-absorbing board, (1.5 ±0.5) mm thick, between capacitor body and liquid solder
Evaluation criteria:	
Visual inspection	No visible damage
$\Delta C/C_0$	2% for MKT/MKP/MFP 5% for EMI suppression capacitors
$\tan \delta$	As specified in sectional specification



## Preliminary Data

### 1.3 General notes on soldering

Permissible heat exposure loads on film capacitors are primarily characterized by the upper category temperature  $T_{max}$ . Long exposure to temperatures above this type-related temperature limit can lead to changes in the plastic dielectric and thus change irreversibly a capacitor's electrical characteristics. For short exposures (as in practical soldering processes) the heat load (and thus the possible effects on a capacitor) will also depend on other factors like:

- Pre-heating temperature and time
- Forced cooling immediately after soldering
- Terminal characteristics:
  - diameter, length, thermal resistance, special configurations (e.g. crimping)
- Height of capacitor above solder bath
- Shadowing by neighboring components
- Additional heating due to heat dissipation by neighboring components
- Use of solder-resist coatings

The overheating associated with some of these factors can usually be reduced by suitable countermeasures. For example, if a pre-heating step cannot be avoided, an additional or reinforced cooling process may possibly have to be included.

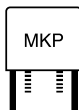
EPCOS recommends the following conditions:

- Pre-heating with a maximum temperature of 110 °C
- Temperature inside the capacitor should not exceed the following limits:
  - MKP/MFP 110 °C
  - MKT 160 °C
- When SMD components are used together with leaded ones, the leaded film capacitors should not pass into the SMD adhesive curing oven. The leaded components should be assembled after the SMD curing step.
- Leaded film capacitors are not suitable for reflow soldering.

### Uncoated capacitors

For uncoated MKT capacitors with lead spacings  $\leq 10$  mm (B32560/B32561) the following measures are recommended:

- pre-heating to not more than 110 °C in the preheater phase
- rapid cooling after soldering


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**MKP AC filtering**
**Preliminary Data**

## 2 Cleaning

To determine whether the following solvents, often used to remove flux residues and other substances, are suitable for the capacitors described, refer to the table below:

Type	Ethanol, isopropanol, n-propanol	n-propanol-water mixtures, water with surface tension-reducing tensides (neutral)	Solvent from table A (see next page)	Solvent from table B (see next page)
MKT (uncoated)	Suitable	Unsuitable	In part suitable	Unsuitable
MKT, MKP, MFP (coated/boxed)		Suitable	Suitable	

Even when suitable solvents are used, a reversible change of the electrical characteristics may occur in uncoated capacitors immediately after they are washed. Thus it is always recommended to dry the components (e.g. 4 h at 70 °C) before they are subjected to subsequent electrical testing.

### Table A

Manufacturers' designations for trifluoro-trichloro-ethane-based cleaning solvents (selection)

Trifluoro-trichloro-ethane	Mixtures of trifluoro-trichloro-ethane with ethanol and isopropanol	Manufacturer
Freon TF	Freon TE 35; Freon TP 35; Freon TES	Du Pont
Frigen 113 TR	Frigen 113 TR-E; Frigen 113 TR-P; Frigen TR-E 35	Hoechst
Arklone P	Arklone A; Arklone L; Arklone K	ICI
Kaltron 113 MDR	Kaltron 113 MDA; Kaltron 113 MDI; Kaltron 113 MDI 35	Kali-Chemie
Flugene 113	Flugene 113 E; Flugene 113 IPA	Rhone-Progil

### Table B (worldwide banned substances)

Manufacturers' designations for unsuitable cleaning solvents (selection)

Mixtures of chlorinated hydrocarbons and ketones with fluorated hydrocarbons	Manufacturer
Freon TMC; Freon TA; Freon TC	Du Pont
Arklone E	ICI
Kaltron 113 MDD; Kaltron 113 MDK	Kali-Chemie
Flugene 113 CM	Rhone-Progil

## Preliminary Data

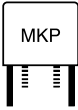
### 3 Embedding of capacitors in finished assemblies

In many applications, finished circuit assemblies are embedded in plastic resins. In this case, both chemical and thermal influences of the embedding ("potting") and curing processes must be taken into account.

Our experience has shown that the following potting materials can be recommended: non-flexible epoxy resins with acid-anhydride hardeners; chemically inert, non-conducting fillers; maximum curing temperature of 100 °C.

#### **Caution:**

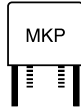
Consult us first if you wish to embed uncoated types!


**B32794 ... B32798**
**MKP AC filtering**
**Preliminary Data**
**Cautions and warnings**

- Do not exceed the upper category temperature (UCT).
- Do not apply any mechanical stress to the capacitor terminals.
- Avoid any compressive, tensile or flexural stress.
- Do not move the capacitor after it has been soldered to the PC board.
- Do not pick up the PC board by the soldered capacitor.
- Do not place the capacitor on a PC board whose PTH hole spacing differs from the specified lead spacing.
- Do not exceed the specified time or temperature limits during soldering.
- Avoid external energy inputs, such as fire or electricity.
- Avoid overload of the capacitors.

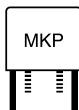
The table below summarizes the safety instructions that must always be observed. A detailed description can be found in the relevant sections of the chapters "General technical information" and "Mounting guidelines".

Topic	Safety information	Reference chapter "General technical information"
Storage conditions	Make sure that capacitors are stored within the specified range of time, temperature and humidity conditions.	4.5 "Storage conditions"
Flammability	Avoid external energy, such as fire or electricity (passive flammability), avoid overload of the capacitors (active flammability) and consider the flammability of materials.	5.3 "Flammability"
Resistance to vibration	Do not exceed the tested ability to withstand vibration. The capacitors are tested to IEC 60068-2-6. EPCOS offers film capacitors specially designed for operation under more severe vibration regimes such as those found in automotive applications. Consult our catalog "Film Capacitors for Automotive Electronics".	5.2 "Resistance to vibration"



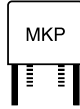
**Preliminary Data**

Topic	Safety information	Reference chapter "Mounting guidelines"
Soldering	Do not exceed the specified time or temperature limits during soldering.	1 "Soldering"
Cleaning	Use only suitable solvents for cleaning capacitors.	2 "Cleaning"
Embedding of capacitors in finished assemblies	When embedding finished circuit assemblies in plastic resins, chemical and thermal influences must be taken into account. Caution: Consult us first, if you also wish to embed other uncoated component types!	3 "Embedding of capacitors in finished assemblies"

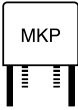

**B32794 ... B32798**
**MKP AC filtering**
**Preliminary Data**
**Symbols and terms**

Symbol	English	German
$\alpha$	Heat transfer coefficient	Wärmeübergangszahl
$\alpha_C$	Temperature coefficient of capacitance	Temperaturkoeffizient der Kapazität
A	Capacitor surface area	Kondensatoroberfläche
$\beta_C$	Humidity coefficient of capacitance	Feuchtekoeffizient der Kapazität
C	Capacitance	Kapazität
$C_R$	Rated capacitance	Nennkapazität
$\Delta C$	Absolute capacitance change	Absolute Kapazitätsänderung
$\Delta C/C$	Relative capacitance change (relative deviation of actual value)	Relative Kapazitätsänderung (relative Abweichung vom Ist-Wert)
$\Delta C/C_R$	Capacitance tolerance (relative deviation from rated capacitance)	Kapazitätstoleranz (relative Abweichung vom Nennwert)
dt	Time differential	Differentielle Zeit
$\Delta t$	Time interval	Zeitintervall
$\Delta T$	Absolute temperature change (self-heating)	Absolute Temperaturänderung (Selbsterwärmung)
$\Delta \tan \delta$	Absolute change of dissipation factor	Absolute Änderung des Verlustfaktors
$\Delta V$	Absolute voltage change	Absolute Spannungsänderung
dV/dt	Time differential of voltage function (rate of voltage rise)	Differentielle Spannungsänderung (Spannungsflankensteilheit)
$\Delta V/\Delta t$	Voltage change per time interval	Spannungsänderung pro Zeitintervall
E	Activation energy for diffusion	Aktivierungsenergie zur Diffusion
ESL	Self-inductance	Eigeninduktivität
ESR	Equivalent series resistance	Ersatz-Serienwiderstand
f	Frequency	Frequenz
$f_1$	Frequency limit for reducing permissible AC voltage due to thermal limits	Grenzfrequenz für thermisch bedingte Reduzierung der zulässigen Wechselspannung
$f_2$	Frequency limit for reducing permissible AC voltage due to current limit	Grenzfrequenz für strombedingte Reduzierung der zulässigen Wechselspannung
$f_r$	Resonant frequency	Resonanzfrequenz
$F_D$	Thermal acceleration factor for diffusion	Therm. Beschleunigungsfaktor zur Diffusion
$F_T$	Derating factor	Deratingfaktor
i	Current (peak)	Stromspitze
$I_C$	Category current (max. continuous current)	Kategoriestrom (max. Dauerstrom)




**Preliminary Data**

Symbol	English	German
$I_{RMS}$	(Sinusoidal) alternating current, root-mean-square value	(Sinusförmiger) Wechselstrom
$i_z$	Capacitance drift	Inkonstanz der Kapazität
$k_0$	Pulse characteristic	Impuls Kennwert
$L_S$	Series inductance	Serieninduktivität
$\lambda$	Failure rate	Ausfallrate
$\lambda_0$	Constant failure rate during useful service life	Konstante Ausfallrate in der Nutzungsphase
$\lambda_{\text{test}}$	Failure rate, determined by tests	Experimentell ermittelte Ausfallrate
$P_{\text{diss}}$	Dissipated power	Abgegebene Verlustleistung
$P_{\text{gen}}$	Generated power	Erzeugte Verlustleistung
$Q$	Heat energy	Wärmeenergie
$\rho$	Density of water vapor in air	Dichte von Wasserdampf in Luft
$R$	Universal molar constant for gases	Allg. Molarkonstante für Gas
$R$	Ohmic resistance of discharge circuit	Ohmscher Widerstand des Entladekreises
$R_i$	Internal resistance	Innenwiderstand
$R_{\text{ins}}$	Insulation resistance	Isolationswiderstand
$R_P$	Parallel resistance	Parallelwiderstand
$R_S$	Series resistance	Serienwiderstand
$S$	severity (humidity test)	Schärfegrad (Feuchtestest)
$t$	Time	Zeit
$T$	Temperature	Temperatur
$\tau$	Time constant	Zeitkonstante
$\tan \delta$	Dissipation factor	Verlustfaktor
$\tan \delta_D$	Dielectric component of dissipation factor	Dielektrischer Anteil des Verlustfaktors
$\tan \delta_P$	Parallel component of dissipation factor	Parallelanteil des Verlustfaktors
$\tan \delta_S$	Series component of dissipation factor	Serienanteil des Verlustfaktors
$T_A$	Ambient temperature	Umgebungstemperatur
$T_{\text{max}}$	Upper category temperature	Obere Kategorietemperatur
$T_{\text{min}}$	Lower category temperature	Untere Kategorietemperatur
$t_{OL}$	Operating life at operating temperature and voltage	Betriebszeit bei Betriebstemperatur und -spannung
$T_{op}$	Operating temperature	Betriebstemperatur
$T_R$	Rated temperature	Nenntemperatur
$T_{ref}$	Reference temperature	Referenztemperatur
$t_{SL}$	Reference service life	Referenz-Lebensdauer
$V_{AC}$	AC voltage	Wechselspannung


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Symbol	English	German
$V_C$	Category voltage	Kategoriespannung
$V_{C,RMS}$	Category AC voltage	(Sinusförmige) Kategorie-Wechselspannung
$V_{CD}$	Corona-discharge onset voltage	Teilentlade-Einsatzspannung
$V_{ch}$	Charging voltage	Ladespannung
$V_{DC}$	DC voltage	Gleichspannung
$V_{FB}$	Fly-back capacitor voltage	Spannung (Flyback)
$V_i$	Input voltage	Eingangsspannung
$V_o$	Output voltage	Ausgangssspannung
$V_{op}$	Operating voltage	Betriebsspannung
$V_p$	Peak pulse voltage	Impuls-Spitzenspannung
$V_{pp}$	Peak-to-peak voltage Impedance	Spannungshub
$V_R$	Rated voltage	Nennspannung
$\hat{V}_R$	Amplitude of rated AC voltage	Amplitude der Nenn-Wechselspannung
$V_{RMS}$	(Sinusoidal) alternating voltage, root-mean-square value	(Sinusförmige) Wechselspannung
$V_{SC}$	S-correction voltage	Spannung bei Anwendung "S-correction"
$V_{sn}$	Snubber capacitor voltage	Spannung bei Anwendung "Beschaltung"
$Z$	Impedance	Scheinwiderstand
$e$	Lead spacing	Rastermaß

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